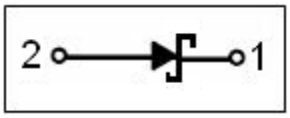
B5817WS-B5819WS

/ Descriptions

/ Features

/ Applications

/ Equivalent Circuit

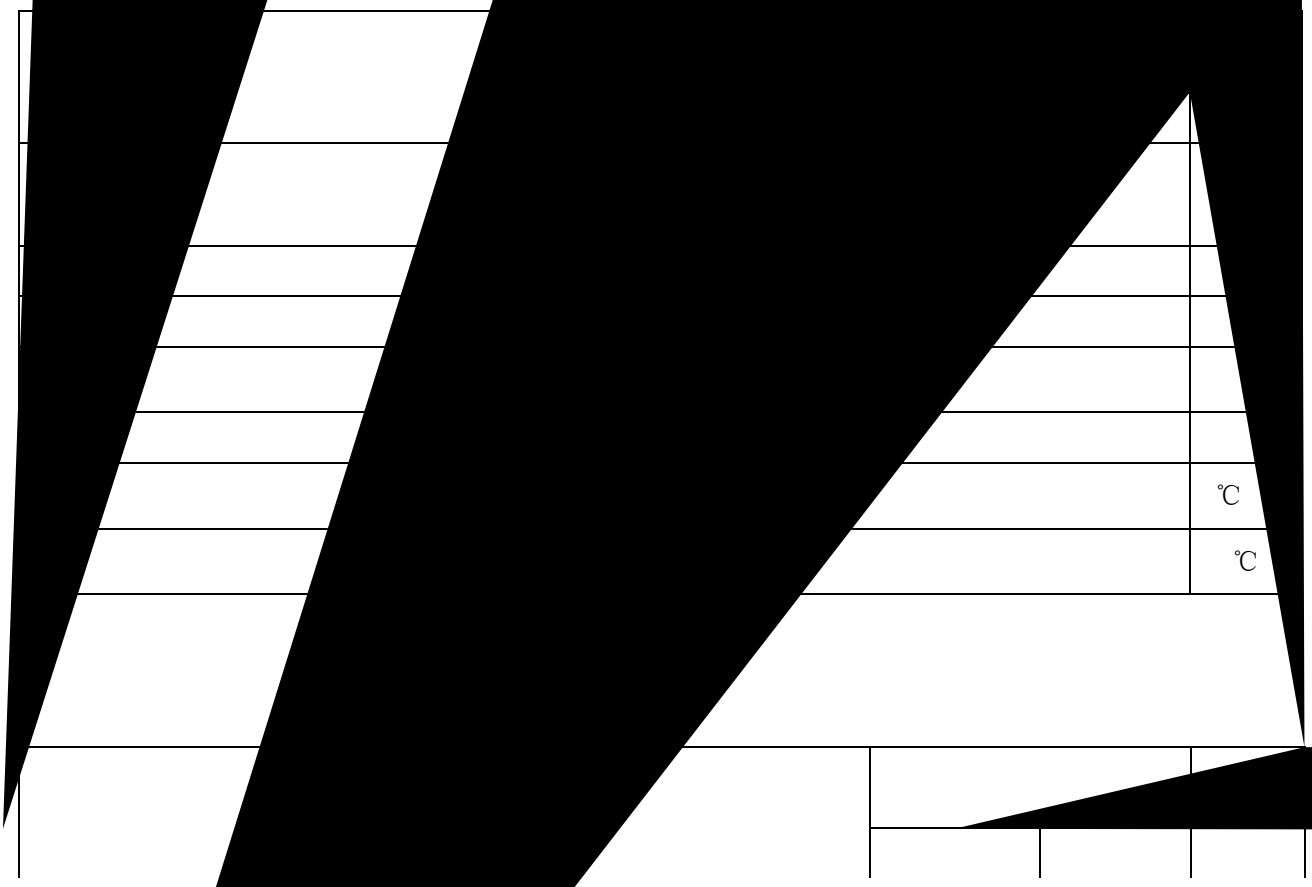


/ Pinning



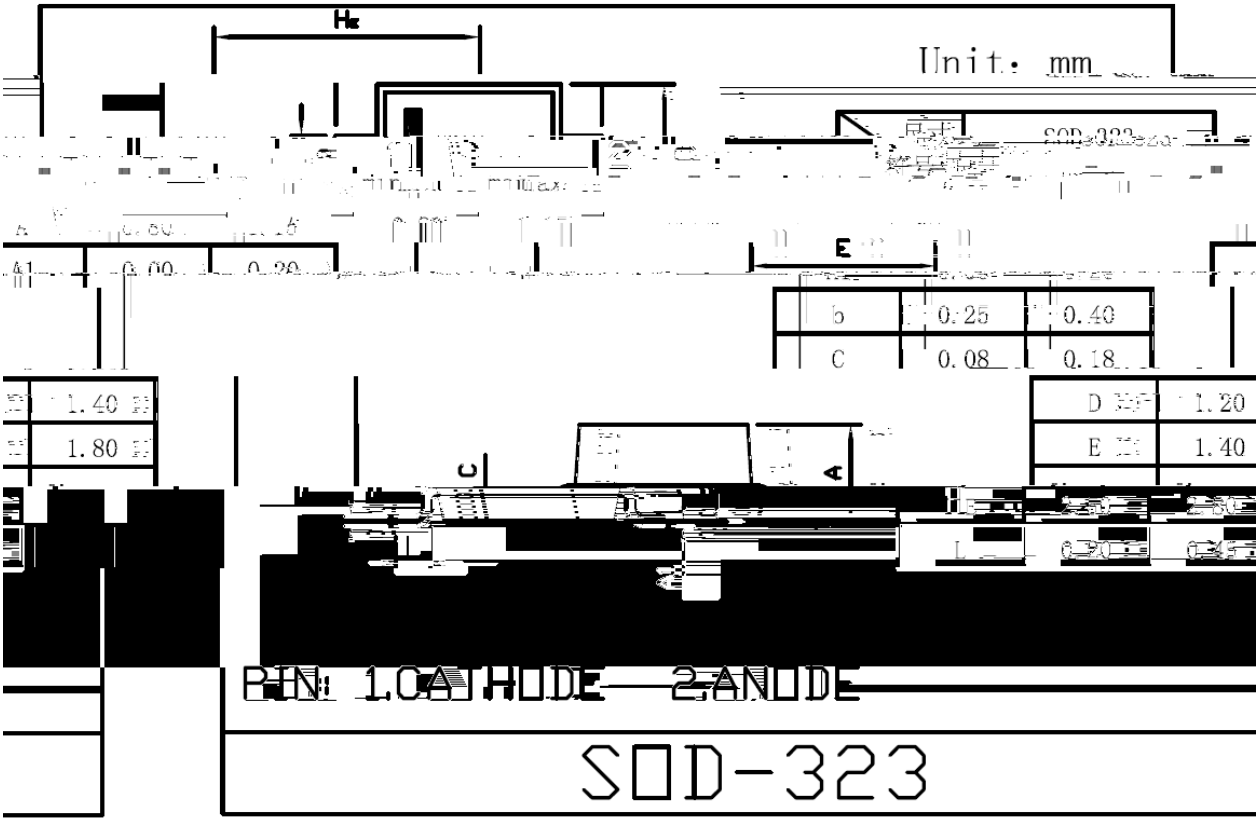
/ Marking

WS

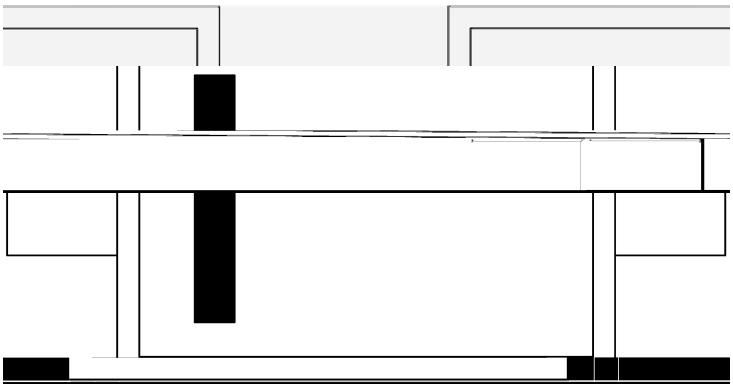


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/ Package Dimensions



/ Marking Instructions



H

SJ

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



℃

± ± ± ℃ ±

℃ ℃

/ Resistance to Soldering Heat Test Conditions

± ℃ ± ± ℃ ±

/ Packaging SPEC.

!	" # $					" % & '		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box (	Outer Box)
SOD-323	3,000	10	30,000	6	180,000	7″ ×8	180×120×180	390×385×205

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